

901 Series

Wakefield-Vette's 900 Series Heat Sinks for Chipset can match up to devices from:
Intel, Broadcom, Xilinx, TI, Motorola, ATI, AMD, Nvidia, Vishay, Powerex, Infineon, Microsemi, and many more.

These heat sinks are designed for air flow applications in the Telecom, Data Center, Networking, Cloud Computing, and many more Industries.

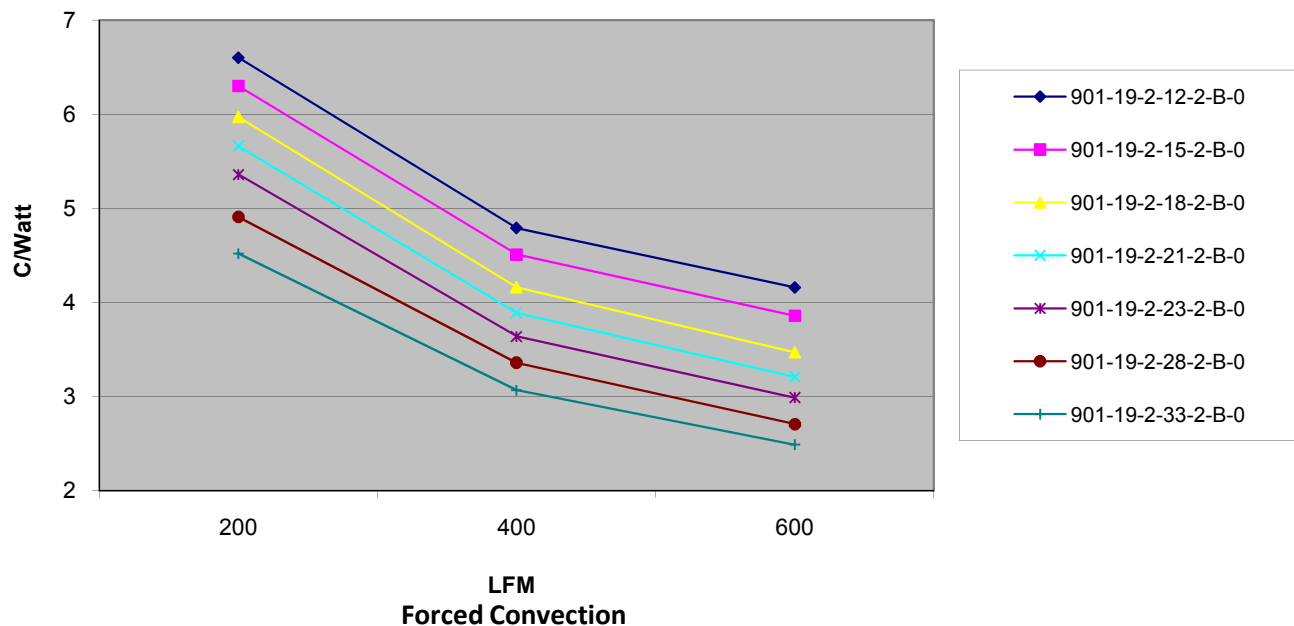
Material: AL 6063

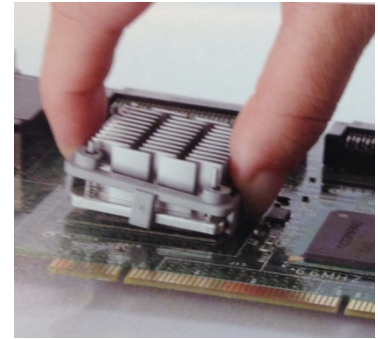
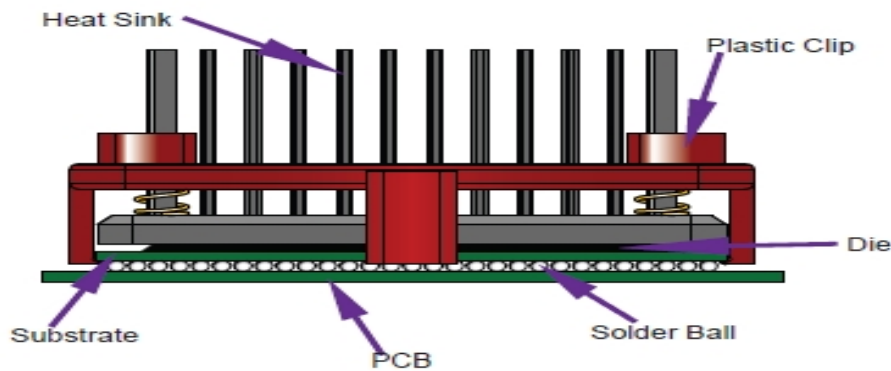
Finish: Black Anodize



| PART # | HEIGHT (mm) | CHIP SIZE (mm) | NATURAL CONVECTION | FORCED CONVECTION (C/W) | | |
|-------------------|-------------|----------------|--------------------|-------------------------|----------|----------|
| | | | | 200 LFM | 400 LFM | 600 LFM |
| 901-19-2-12-2-B-0 | 12 | 19 | 12.74 C/W | 6.6 C/W | 4.79 C/W | 4.16 C/W |
| 901-19-2-15-2-B-0 | 15 | 19 | 12.05 C/W | 6.3 C/W | 4.51 C/W | 3.86 C/W |
| 901-19-2-18-2-B-0 | 18 | 19 | 11.35 C/W | 5.97 C/W | 4.16 C/W | 3.47 C/W |
| 901-19-2-21-2-B-0 | 21 | 19 | 10.66 C/W | 5.66 C/W | 3.89 C/W | 3.21 C/W |
| 901-19-2-23-2-B-0 | 23 | 19 | 10.55 C/W | 5.36 C/W | 3.64 C/W | 2.99 C/W |
| 901-19-2-28-2-B-0 | 28 | 19 | 10.27 C/W | 4.91 C/W | 3.36 C/W | 2.71 C/W |
| 901-19-2-33-2-B-0 | 33 | 19 | 9.99 C/W | 4.52 C/W | 3.07 C/W | 2.49 C/W |

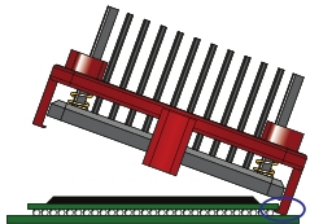
THERMAL PERFORMANCE:



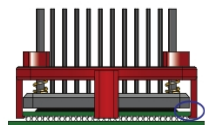
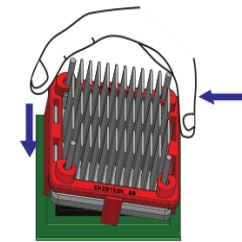


Wakefield-Vette's heat sink assemblies onto chip set using the space that is between the PCB and the substrate of the solder balls. The solder balls provide a minimal gap of .5mm to .7mm. Attachment feature is below a .4mm thickness. The clipping system will not interfere or damage chip. Contact area is the edge of chip.

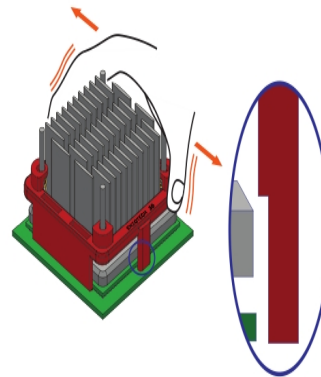
ASSEMBLY INSTRUCTION:



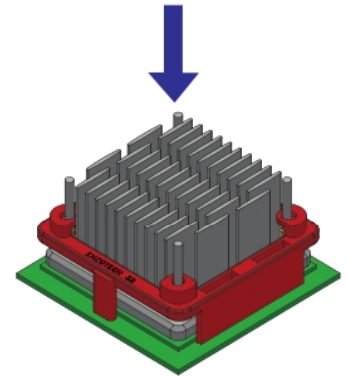
Step 1: Hook the clip under one side of the BGA chip set.



Step 2: Rotate assembly down until opposite side clip engages substrate edge of BGA chip set.



Step 3: Make sure the solder rods are clearing from edges of BGA chip set.



Step 4: Press firmly down to make sure clips fully engage edges of chip set. Heat Sink should not move around easily.

Random Vibration Test

Frequency : 5 Hz to 500 Hz
 Acceleration : 3.13 grms
 P.S.D : 0.01 g²/HZ (5 Hz)
 0.02 g²/HZ (20 Hz to 500 Hz)
 Test Axis : X, Y, Z axis
 Test Time : 10 mins (Each axis)
 Total Test Time : 30 mins

SHOCK TEST SPECIFICATION :

Wave Form : Half sine wave
 Acceleration : 50 g
 Duration Time : 11 ms
 No. of Shock : Each axis 3 times
 Shock Direction : $\pm X$, $\pm Y$, $\pm Z$ axis
 Reliability & Communication
 Testing Instruments